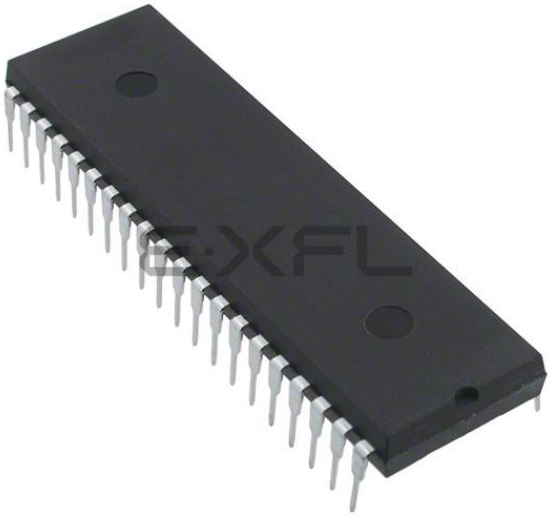

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	16KB (8K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c44-16-p

5.0 INTERRUPTS

The PIC17C4X devices have 11 sources of interrupt:

- External interrupt from the RA0/INT pin
- Change on RB7:RB0 pins
- TMR0 Overflow
- TMR1 Overflow
- TMR2 Overflow
- TMR3 Overflow
- USART Transmit buffer empty
- USART Receive buffer full
- Capture1
- Capture2
- T0CKI edge occurred

There are four registers used in the control and status of interrupts. These are:

- CPUSTA
- INTSTA
- PIE
- PIR

The CPUSTA register contains the GLINTD bit. This is the Global Interrupt Disable bit. When this bit is set, all interrupts are disabled. This bit is part of the controller core functionality and is described in the Memory Organization section.

When an interrupt is responded to, the GLINTD bit is automatically set to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with the interrupt vector address. There are four interrupt vectors. Each vector address is for a specific interrupt source (except the peripheral interrupts which have the same vector address). These sources are:

- External interrupt from the RA0/INT pin
- TMR0 Overflow
- T0CKI edge occurred
- Any peripheral interrupt

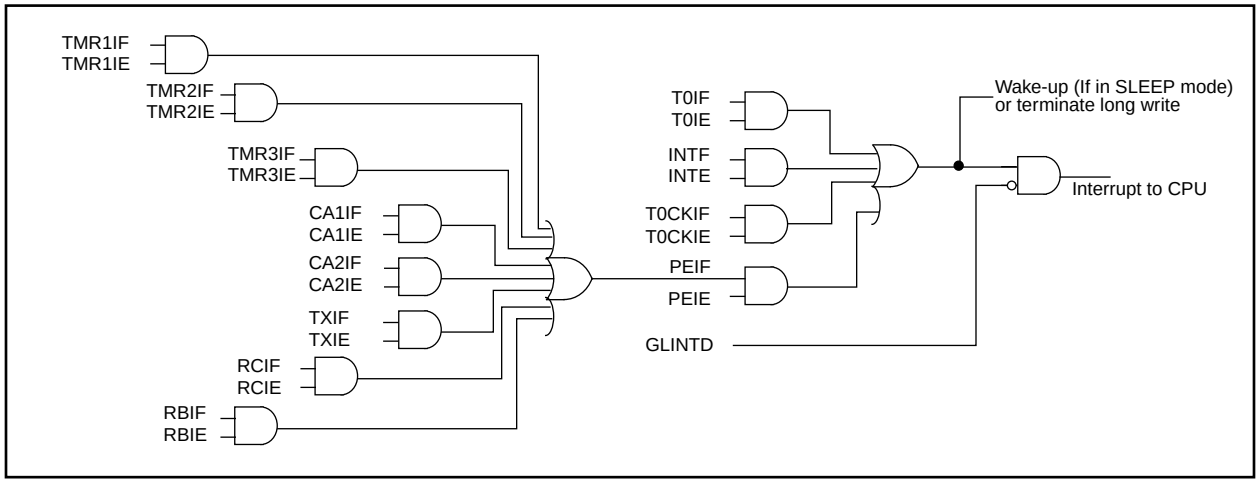
When program execution vectors to one of these interrupt vector addresses (except for the peripheral interrupt address), the interrupt flag bit is automatically cleared. Vectoring to the peripheral interrupt vector address does not automatically clear the source of the interrupt. In the peripheral interrupt service routine, the source(s) of the interrupt can be determined by testing the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests.

All of the individual interrupt flag bits will be set regardless of the status of their corresponding mask bit or the GLINTD bit.

For external interrupt events, there will be an interrupt latency. For two cycle instructions, the latency could be one instruction cycle longer.

The “return from interrupt” instruction, `RETFIE`, can be used to mark the end of the interrupt service routine. When this instruction is executed, the stack is “POPed”, and the GLINTD bit is cleared (to re-enable interrupts).

FIGURE 5-1: INTERRUPT LOGIC



5.3 Peripheral Interrupt Request Register (PIR)

This register contains the individual flag bits for the peripheral interrupts.

Note: These bits will be set by the specified condition, even if the corresponding interrupt enable bit is cleared (interrupt disabled), or the GLINTD bit is set (all interrupts disabled). Before enabling an interrupt, the user may wish to clear the interrupt flag to ensure that the program does not immediately branch to the peripheral interrupt service routine.

FIGURE 5-4: PIR REGISTER (ADDRESS: 16h, BANK 1)

R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R - 1	R - 0
RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF
bit7							bit0

R = Readable bit
W = Writable bit
-n = Value at POR reset

bit 7: **RBIF**: PORTB Interrupt on Change Flag bit
1 = One of the PORTB inputs changed (Software must end the mismatch condition)
0 = None of the PORTB inputs have changed

bit 6: **TMR3IF**: Timer3 Interrupt Flag bit
If Capture1 is enabled (CA1/$\overline{PR3}$ = 1)
1 = Timer3 overflowed
0 = Timer3 did not overflow

If Capture1 is disabled (CA1/$\overline{PR3}$ = 0)
1 = Timer3 value has rolled over to 0000h from equalling the period register (PR3H:PR3L) value
0 = Timer3 value has not rolled over to 0000h from equalling the period register (PR3H:PR3L) value

bit 5: **TMR2IF**: Timer2 Interrupt Flag bit
1 = Timer2 value has rolled over to 0000h from equalling the period register (PR2) value
0 = Timer2 value has not rolled over to 0000h from equalling the period register (PR2) value

bit 4: **TMR1IF**: Timer1 Interrupt Flag bit
If Timer1 is in 8-bit mode (T16 = 0)
1 = Timer1 value has rolled over to 0000h from equalling the period register (PR) value
0 = Timer1 value has not rolled over to 0000h from equalling the period register (PR2) value

If Timer1 is in 16-bit mode (T16 = 1)
1 = TMR1:TMR2 value has rolled over to 0000h from equalling the period register (PR1:PR2) value
0 = TMR1:TMR2 value has not rolled over to 0000h from equalling the period register (PR1:PR2) value

bit 3: **CA2IF**: Capture2 Interrupt Flag bit
1 = Capture event occurred on RB1/CAP2 pin
0 = Capture event did not occur on RB1/CAP2 pin

bit 2: **CA1IF**: Capture1 Interrupt Flag bit
1 = Capture event occurred on RB0/CAP1 pin
0 = Capture event did not occur on RB0/CAP1 pin

bit 1: **TXIF**: USART Transmit Interrupt Flag bit
1 = Transmit buffer is empty
0 = Transmit buffer is full

bit 0: **RCIF**: USART Receive Interrupt Flag bit
1 = Receive buffer is full
0 = Receive buffer is empty

9.0 I/O PORTS

The PIC17C4X devices have five I/O ports, PORTA through PORTE. PORTB through PORTE have a corresponding Data Direction Register (DDR), which is used to configure the port pins as inputs or outputs. These five ports are made up of 33 I/O pins. Some of these ports pins are multiplexed with alternate functions.

PORTC, PORTD, and PORTE are multiplexed with the system bus. These pins are configured as the system bus when the device's configuration bits are selected to Microprocessor or Extended Microcontroller modes. In the two other microcontroller modes, these pins are general purpose I/O.

PORTA and PORTB are multiplexed with the peripheral features of the device. These peripheral features are:

- Timer modules
- Capture module
- PWM module
- USART/SCI module
- External Interrupt pin

When some of these peripheral modules are turned on, the port pin will automatically configure to the alternate function. The modules that do this are:

- PWM module
- USART/SCI module

When a pin is automatically configured as an output by a peripheral module, the pins data direction (DDR) bit is unknown. After disabling the peripheral module, the user should re-initialize the DDR bit to the desired configuration.

The other peripheral modules (which require an input) must have their data direction bit configured appropriately.

Note:	A pin that is a peripheral input, can be configured as an output (DDRx<y> is cleared). The peripheral events will be determined by the action output on the port pin.

9.1 PORTA Register

PORTA is a 6-bit wide latch. PORTA does not have a corresponding Data Direction Register (DDR).

Reading PORTA reads the status of the pins.

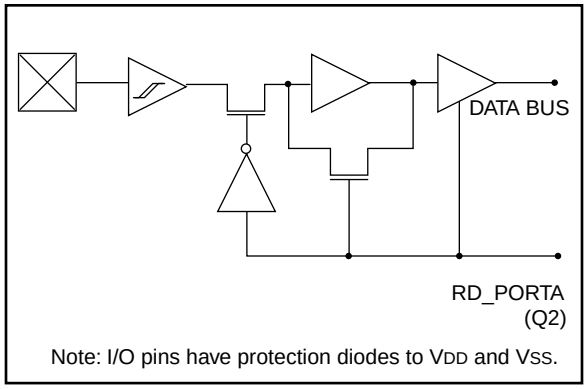
The RA1 pin is multiplexed with TMR0 clock input, and RA4 and RA5 are multiplexed with the USART functions. The control of RA4 and RA5 as outputs is automatically configured by the USART module.

9.1.1 USING RA2, RA3 AS OUTPUTS

The RA2 and RA3 pins are open drain outputs. To use the RA2 or the RA3 pin(s) as output(s), simply write to the PORTA register the desired value. A '0' will cause the pin to drive low, while a '1' will cause the pin to float (hi-impedance). An external pull-up resistor should be used to pull the pin high. Writes to PORTA will not affect the other pins.

Note:	When using the RA2 or RA3 pin(s) as output(s), read-modify-write instructions (such as BCF, BSF, BTG) on PORTA are not recommended. Such operations read the port pins, do the desired operation, and then write this value to the data latch. This may inadvertently cause the RA2 or RA3 pins to switch from input to output (or vice-versa). It is recommended to use a shadow register for PORTA. Do the bit operations on this shadow register and then move it to PORTA.

FIGURE 9-1: RA0 AND RA1 BLOCK DIAGRAM



Note: I/O pins have protection diodes to VDD and VSS.

12.1 Timer1 and Timer2

12.1.1 TIMER1, TIMER2 IN 8-BIT MODE

Both Timer1 and Timer2 will operate in 8-bit mode when the T16 bit is clear. These two timers can be independently configured to increment from the internal instruction cycle clock or from an external clock source on the RB4/TCLK12 pin. The timer clock source is configured by the TMRxCS bit (x = 1 for Timer1 or = 2 for Timer2). When TMRxCS is clear, the clock source is internal and increments once every instruction cycle (Fosc/4). When TMRxCS is set, the clock source is the RB4/TCLK12 pin, and the timer will increment on every falling edge of the RB4/TCLK12 pin.

The timer increments from 00h until it equals the Period register (PRx). It then resets to 00h at the next increment cycle. The timer interrupt flag is set when the timer is reset. TMR1 and TMR2 have individual interrupt flag bits. The TMR1 interrupt flag bit is latched into TMR1IF, and the TMR2 interrupt flag bit is latched into TMR2IF.

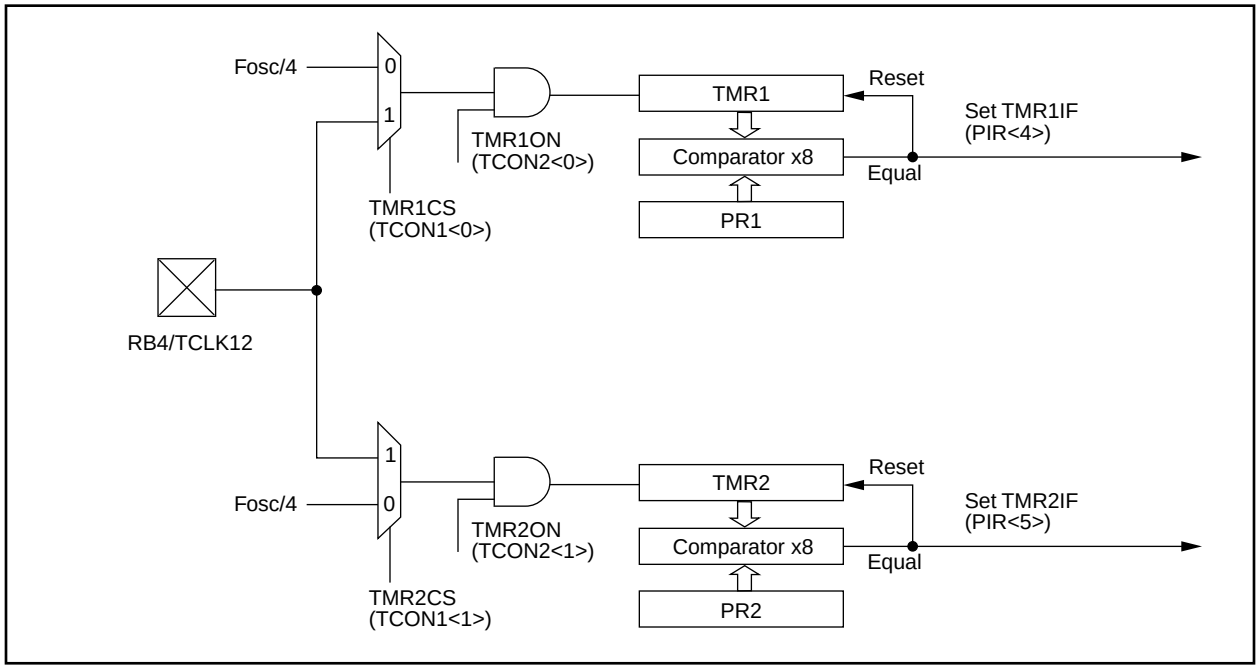
Each timer also has a corresponding interrupt enable bit (TMRxIE). The timer interrupt can be enabled by setting this bit and disabled by clearing this bit. For peripheral interrupts to be enabled, the Peripheral Interrupt Enable bit must be enabled (PEIE is set) and global interrupts must be enabled (GLINTD is cleared).

The timers can be turned on and off under software control. When the Timerx On control bit (TMRxON) is set, the timer increments from the clock source. When TMRxON is cleared, the timer is turned off and cannot cause the timer interrupt flag to be set.

12.1.1.1 EXTERNAL CLOCK INPUT FOR TIMER1 OR TIMER2

When TMRxCS is set, the clock source is the RB4/TCLK12 pin, and the timer will increment on every falling edge on the RB4/TCLK12 pin. The TCLK12 input is synchronized with internal phase clocks. This causes a delay from the time a falling edge appears on TCLK12 to the time TMR1 or TMR2 is actually incremented. For the external clock input timing requirements, see the Electrical Specification section.

FIGURE 12-3: TIMER1 AND TIMER2 IN TWO 8-BIT TIMER/COUNTER MODE

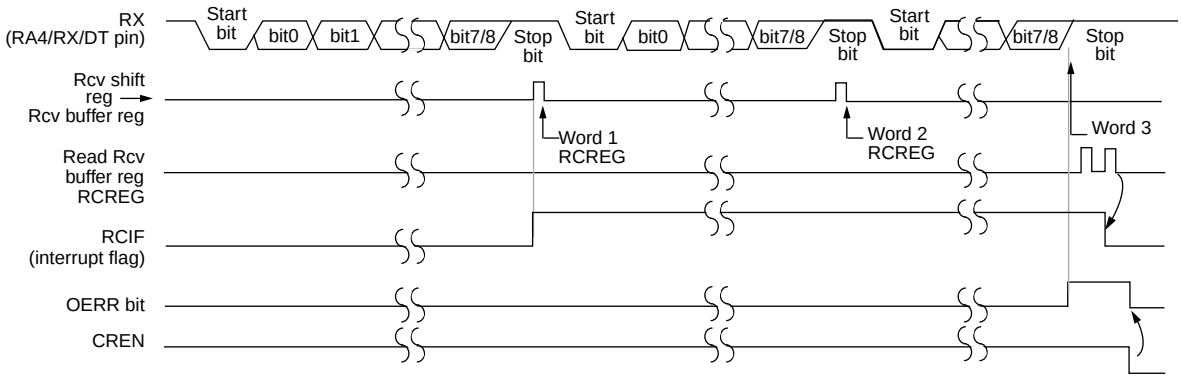


Steps to follow when setting up an Asynchronous Reception:

1. Initialize the SPBRG register for the appropriate baud rate.
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If interrupts are desired, then set the RCIE bit.
4. If 9-bit reception is desired, then set the RX9 bit.
5. Enable the reception by setting the CREN bit.
6. The RCIF bit will be set when reception completes and an interrupt will be generated if the RCIE bit was set.
7. Read RCSTA to get the ninth bit (if enabled) and FERR bit to determine if any error occurred during reception.
8. Read RCREG for the 8-bit received data.
9. If an overrun error occurred, clear the error by clearing the OERR bit.

Note: To terminate a reception, either clear the SREN and CREN bits, or the SPEN bit. This will reset the receive logic, so that it will be in the proper state when receive is re-enabled.

FIGURE 13-8: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

TABLE 13-6: REGISTERS ASSOCIATED WITH ASYNCHRONOUS RECEPTION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
16h, Bank 1	PIR	RBIF	TMR3IF	TMR2IF	TMR1IF	CA2IF	CA1IF	TXIF	RCIF	0000 0010	0000 0010
13h, Bank 0	RCSTA	SPEN	RX9	SREN	CREN	—	FERR	OERR	RX9D	0000 -00x	0000 -00u
14h, Bank 0	RCREG	RX7	RX6	RX5	RX4	RX3	RX2	RX1	RX0	xxxx xxxx	uuuu uuuu
17h, Bank 1	PIE	RBIE	TMR3IE	TMR2IE	TMR1IE	CA2IE	CA1IE	TXIE	RCIE	0000 0000	0000 0000
15h, Bank 0	TXSTA	CSRC	TX9	TXEN	SYNC	—	—	TRMT	TX9D	0000 --1x	0000 --1u
17h, Bank 0	SPBRG	Baud rate generator register								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as a '0', shaded cells are not used for asynchronous reception.
Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.

FIGURE 14-3: CRYSTAL OPERATION, OVERTONE CRYSTALS (XT OSC CONFIGURATION)

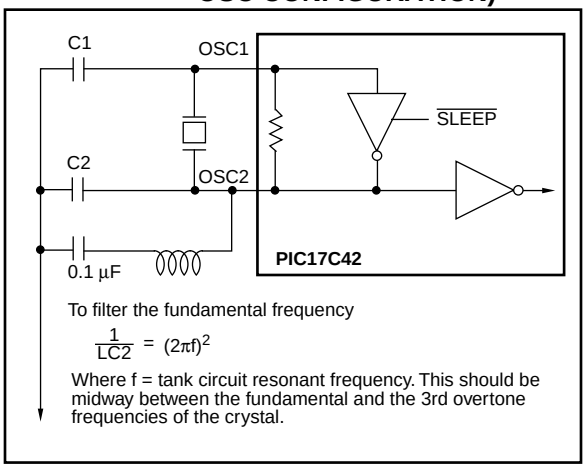


TABLE 14-2: CAPACITOR SELECTION FOR CERAMIC RESONATORS

Oscillator Type	Resonator Frequency	Capacitor Range C1 = C2
LF	455 kHz 2.0 MHz	15 - 68 pF 10 - 33 pF
XT	4.0 MHz 8.0 MHz 16.0 MHz	22 - 68 pF 33 - 100 pF 33 - 100 pF
Higher capacitance increases the stability of the oscillator but also increases the start-up time. These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.		
Resonators Used:		
455 kHz	Panasonic EFO-A455K04B	± 0.3%
2.0 MHz	Murata Erie CSA2.00MG	± 0.5%
4.0 MHz	Murata Erie CSA4.00MG	± 0.5%
8.0 MHz	Murata Erie CSA8.00MT	± 0.5%
16.0 MHz	Murata Erie CSA16.00MX	± 0.5%
Resonators used did not have built-in capacitors.		

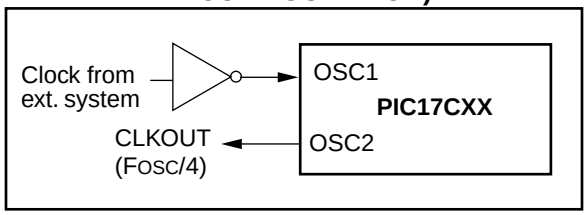
TABLE 14-3: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

Osc Type	Freq	C1	C2
LF	32 kHz(1) 1 MHz 2 MHz	100-150 pF 10-33 pF 10-33 pF	100-150 pF 10-33 pF 10-33 pF
XT	2 MHz 4 MHz 8 MHz (2) 16 MHz 25 MHz 32 MHz (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)	47-100 pF 15-68 pF 15-47 pF TBD 15-47 pF 0 (3)
Higher capacitance increases the stability of the oscillator but also increases the start-up time and the oscillator current. These values are for design guidance only. RS may be required in XT mode to avoid overdriving the crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values for external components. Note 1: For VDD > 4.5V, C1 = C2 ≈ 30 pF is recommended. 2: RS of 330Ω is required for a capacitor combination of 15/15 pF. 3: Only the capacitance of the board was present.			
Crystals Used:			
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM	
1.0 MHz	ECS-10-13-1	± 50 PPM	
2.0 MHz	ECS-20-20-1	± 50 PPM	
4.0 MHz	ECS-40-20-1	± 50 PPM	
8.0 MHz	ECS ECS-80-S-4 ECS-80-18-1	± 50 PPM	
16.0 MHz	ECS-160-20-1	TBD	
25 MHz	CTS CTS25M	± 50 PPM	
32 MHz	CRYSTEK HF-2	± 50 PPM	

14.2.3 EXTERNAL CLOCK OSCILLATOR

In the EC oscillator mode, the OSC1 input can be driven by CMOS drivers. In this mode, the OSC1/CLKIN pin is hi-impedance and the OSC2/CLKOUT pin is the CLKOUT output (4 TOSC).

FIGURE 14-4: EXTERNAL CLOCK INPUT OPERATION (EC OSC CONFIGURATION)



ANDWF **AND WREG with f**

Syntax: [*label*] ANDWF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (WREG) .AND. (f) → (dest)

Status Affected: Z

Encoding:

0000	101d	ffff	ffff

Description: The contents of WREG are AND'ed with register 'f'. If 'd' is 0 the result is stored in WREG. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `ANDWF REG, 1`

Before Instruction
WREG = 0x17
REG = 0xC2

After Instruction
WREG = 0x17
REG = 0x02

BCF **Bit Clear f**

Syntax: [*label*] BCF f,b

Operands: $0 \le f \le 255$
$0 \le b \le 7$

Operation: 0 → (f<b>)

Status Affected: None

Encoding:

1000	1bbb	ffff	ffff

Description: Bit 'b' in register 'f' is cleared.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register 'f'

Example: `BCF FLAG_REG, 7`

Before Instruction
FLAG_REG = 0xC7

After Instruction
FLAG_REG = 0x47

Applicable Devices	42	R42	42A	43	R43	44

17.0 PIC17C42 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125˚C

Storage temperature ..... -65˚C to +150˚C

Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V

Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +12V

Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V

Total power dissipation (Note 1) 1.0W

Maximum current out of V_{SS} pin(s) - Total ..... 250 mA

Maximum current into V_{DD} pin(s) - Total ..... 200 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA

Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA

Maximum output current sunk by RA2 or RA3 pins ..... 60 mA

Maximum output current sourced by any I/O pin ..... 20 mA

Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA

Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA

Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA

Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

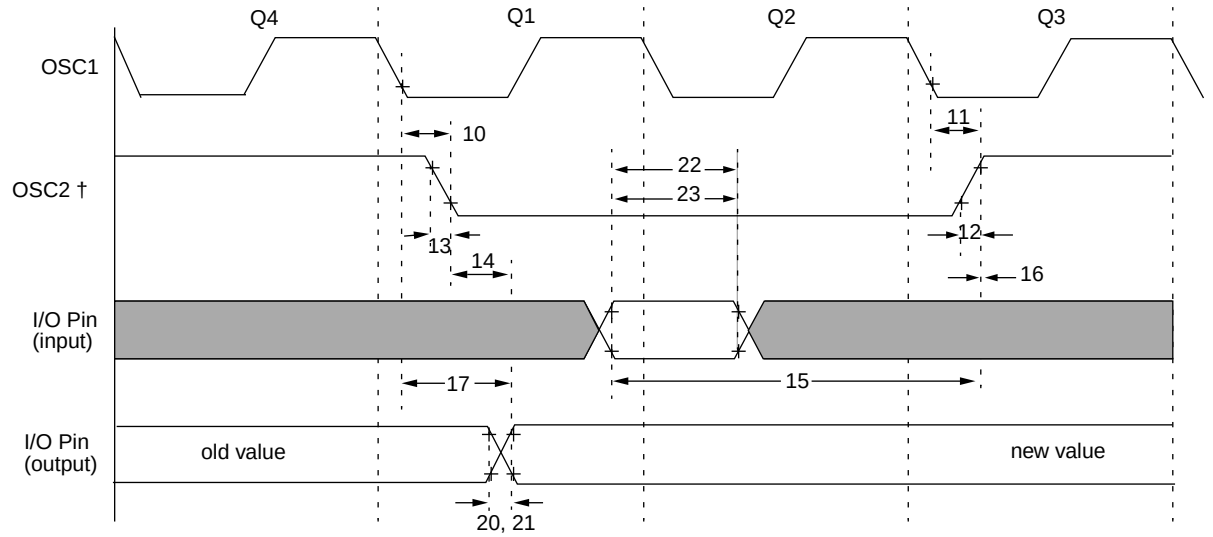
Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 17-3: CLKOUT AND I/O TIMING



† In EC and RC modes only.

TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	—	15 ‡	30 ‡	ns	Note 1
11	TosH2ckH	OSC1↑ to CLKOUT↑	—	15 ‡	30 ‡	ns	Note 1
12	TckR	CLKOUT rise time	—	5 ‡	15 ‡	ns	Note 1
13	TckF	CLKOUT fall time	—	5 ‡	15 ‡	ns	Note 1
14	TckH2ioV	CLKOUT↑ to Port out valid	—	—	0.5TCY + 20‡	ns	Note 1
15	TioV2ckH	Port in valid before CLKOUT↑	0.25TCY + 25 ‡	—	—	ns	Note 1
16	TckH2ioI	Port in hold after CLKOUT↑	0 ‡	—	—	ns	Note 1
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	100 ‡	ns	
20	TioR	Port output rise time	—	10 ‡	35 ‡	ns	
21	TioF	Port output fall time	—	10 ‡	35 ‡	ns	
22	TinHL	INT pin high or low time	25 *	—	—	ns	
23	TrbHL	RB7:RB0 change INT high or low time	25 *	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Measurements are taken in EC Mode where OSC2 output = 4 x TOSC = TCY.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

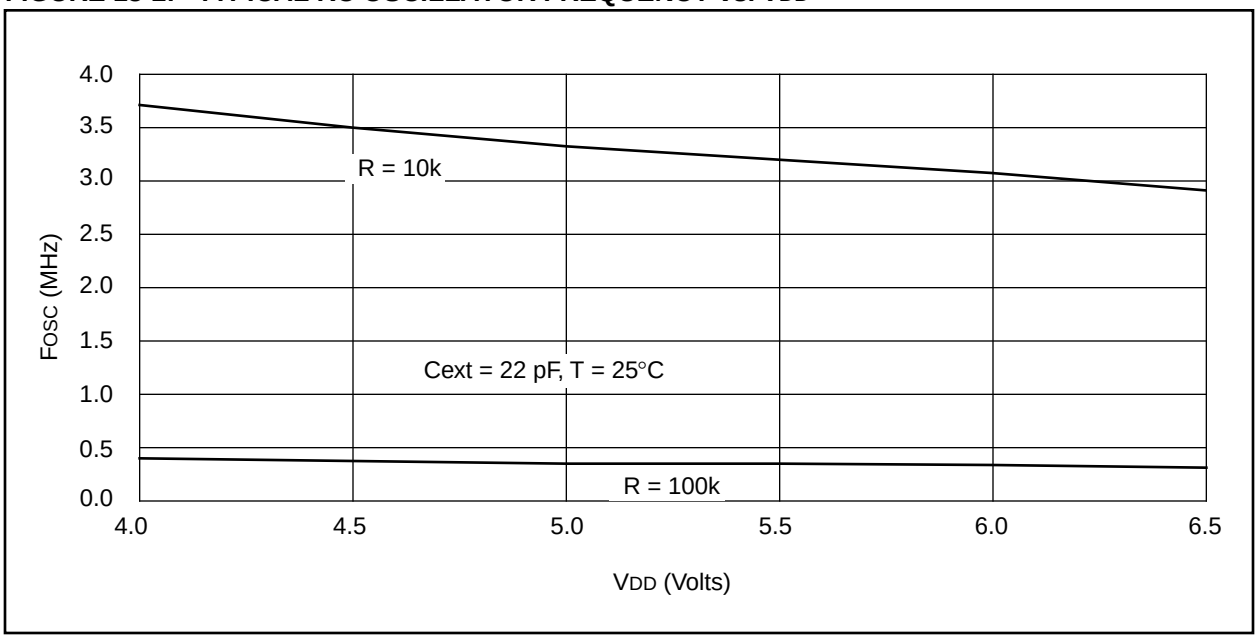
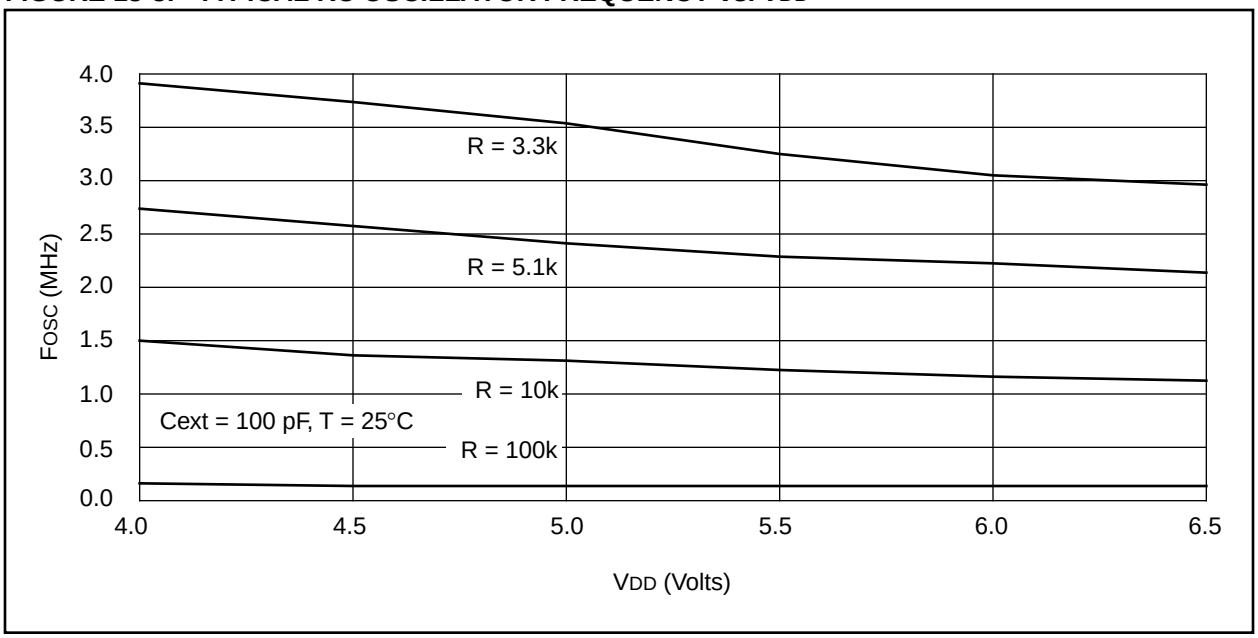
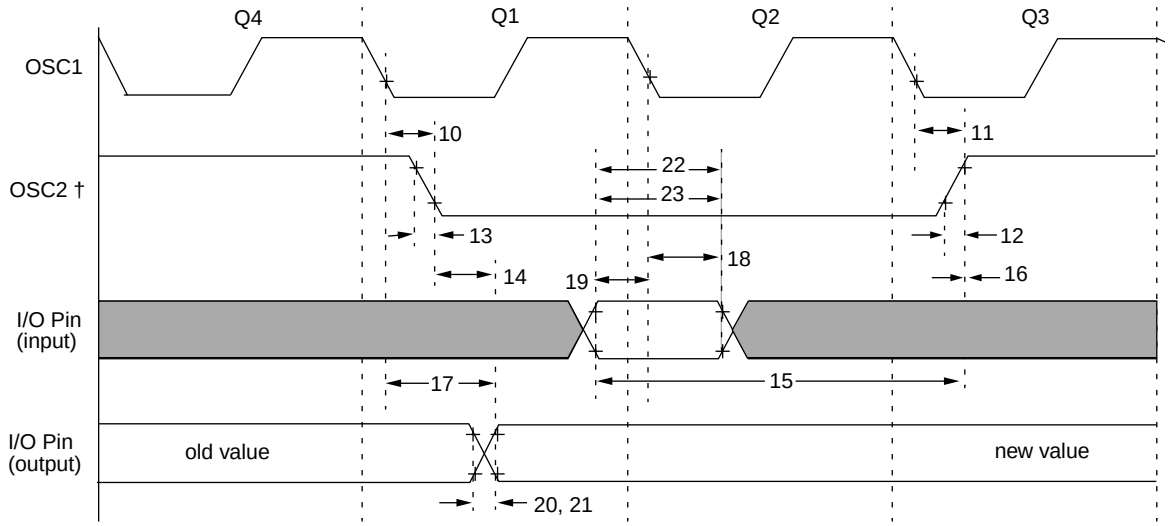


FIGURE 18-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-3: CLKOUT AND I/O TIMING



† In EC and RC modes only.

TABLE 19-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↓ to CLKOUT↓		—	15 ‡	30 ‡	ns	Note 1
11	TosH2ckH	OSC1↓ to CLKOUT↑		—	15 ‡	30 ‡	ns	Note 1
12	TckR	CLKOUT rise time		—	5 ‡	15 ‡	ns	Note 1
13	TckF	CLKOUT fall time		—	5 ‡	15 ‡	ns	Note 1
14	TckH2ioV	CLKOUT ↑ to Port out valid	PIC17CR42/42A/43/ R43/44	—	—	0.5TCY + 20 ‡	ns	Note 1
			PIC17LCR42/42A/43/ R43/44	—	—	0.5TCY + 50 ‡	ns	Note 1
15	TioV2ckH	Port in valid before CLKOUT↑	PIC17CR42/42A/43/ R43/44	0.25TCY + 25 ‡	—	—	ns	Note 1
			PIC17LCR42/42A/43/ R43/44	0.25TCY + 50 ‡	—	—	ns	Note 1
16	TckH2ioI	Port in hold after CLKOUT↑		0 ‡	—	—	ns	Note 1
17	TosH2ioV	OSC1↓ (Q1 cycle) to Port out valid		—	—	100 ‡	ns	
18	TosH2ioI	OSC1↓ (Q2 cycle) to Port input invalid (I/O in hold time)		0 ‡	—	—	ns	
19	TioV2osH	Port input valid to OSC1↓ (I/O in setup time)		30 ‡	—	—	ns	
20	TioR	Port output rise time		—	10 ‡	35 ‡	ns	
21	TioF	Port output fall time		—	10 ‡	35 ‡	ns	
22	TinHL	INT pin high or low time		25 *	—	—	ns	
23	TrbHL	RB7:RB0 change INT high or low time		25 *	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Measurements are taken in EC Mode where CLKOUT output is 4 x TOSC.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-2: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD

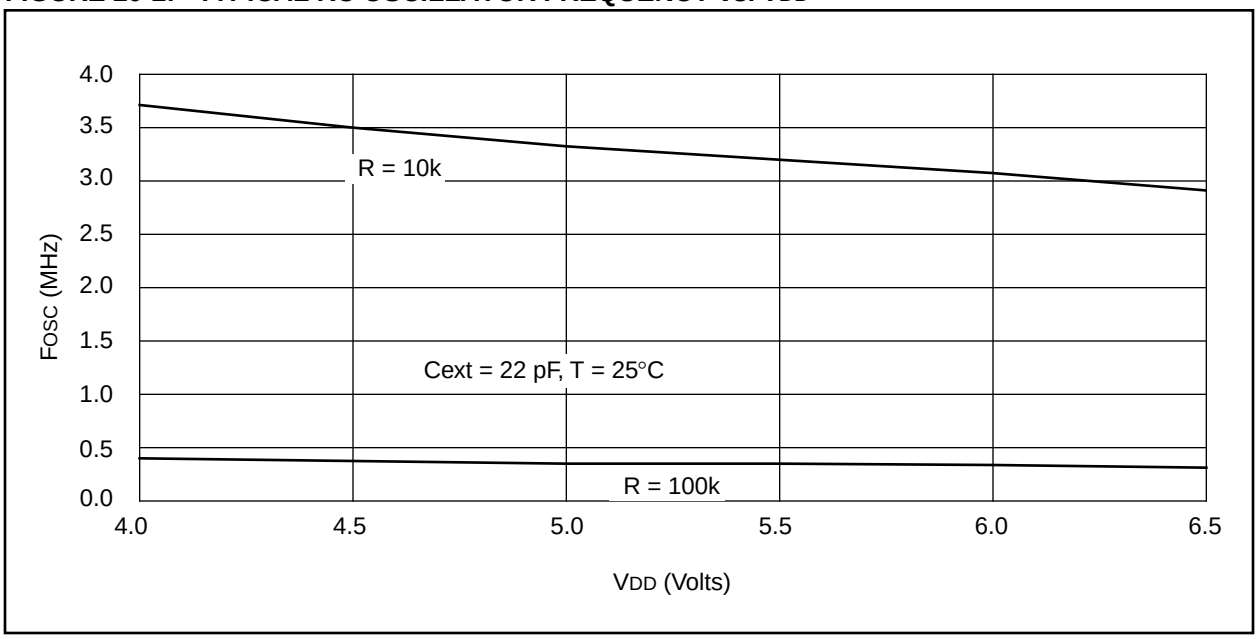
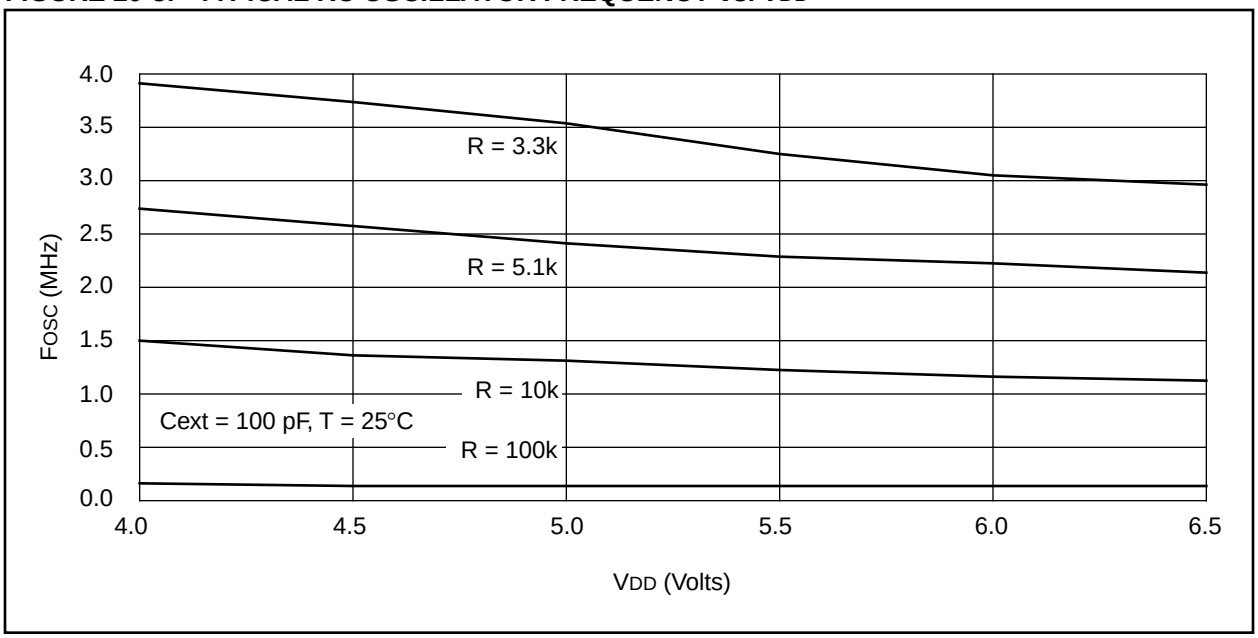


FIGURE 20-3: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

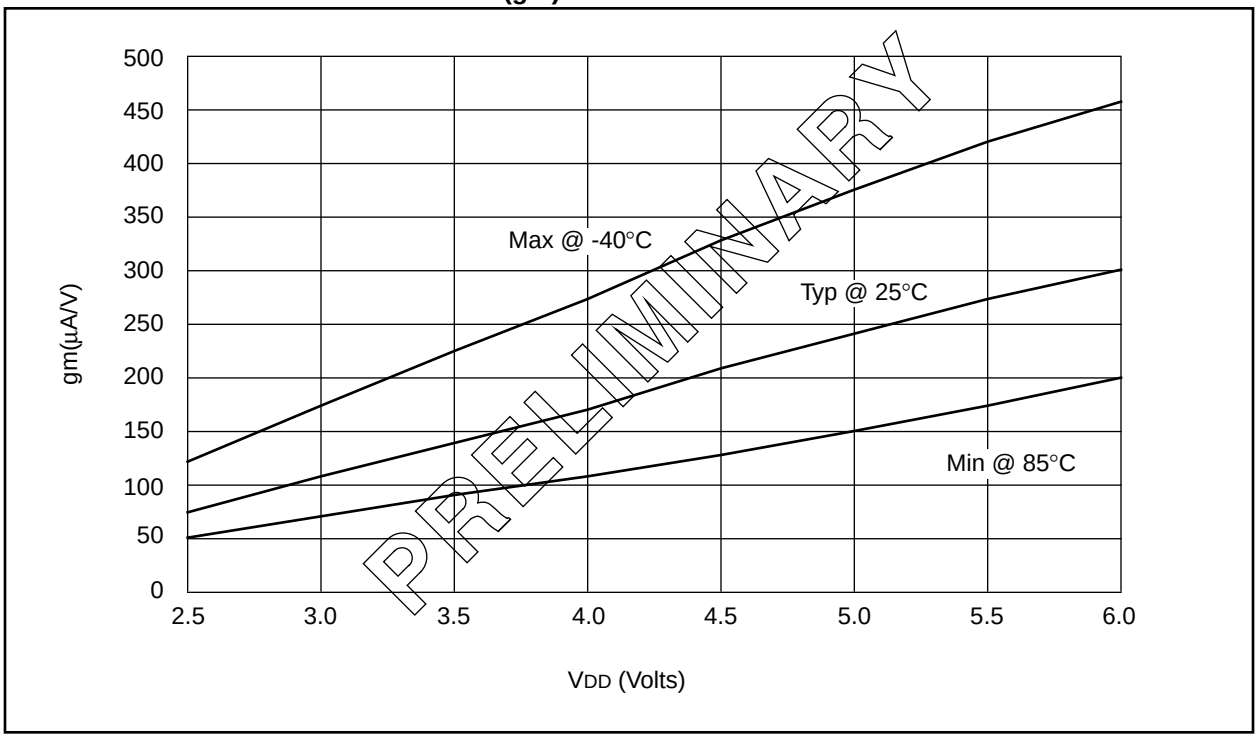
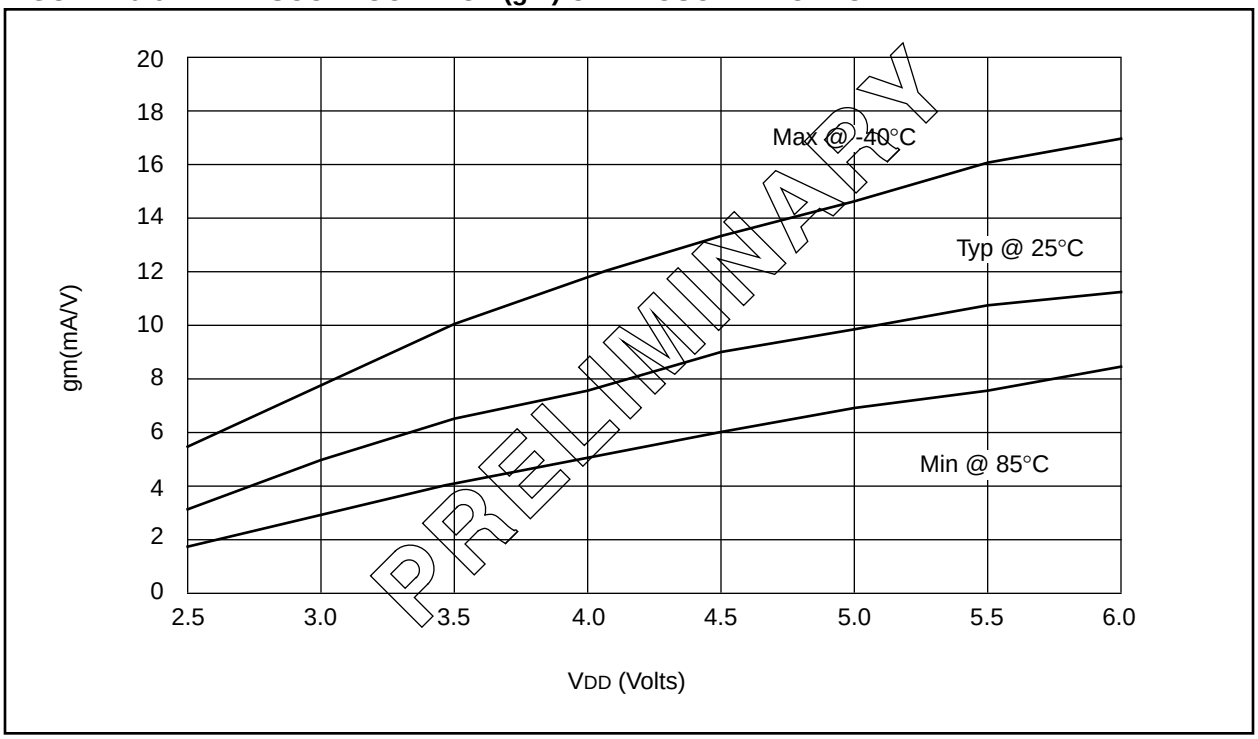


FIGURE 20-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 20-15: IOH vs. VOH, VDD = 5V

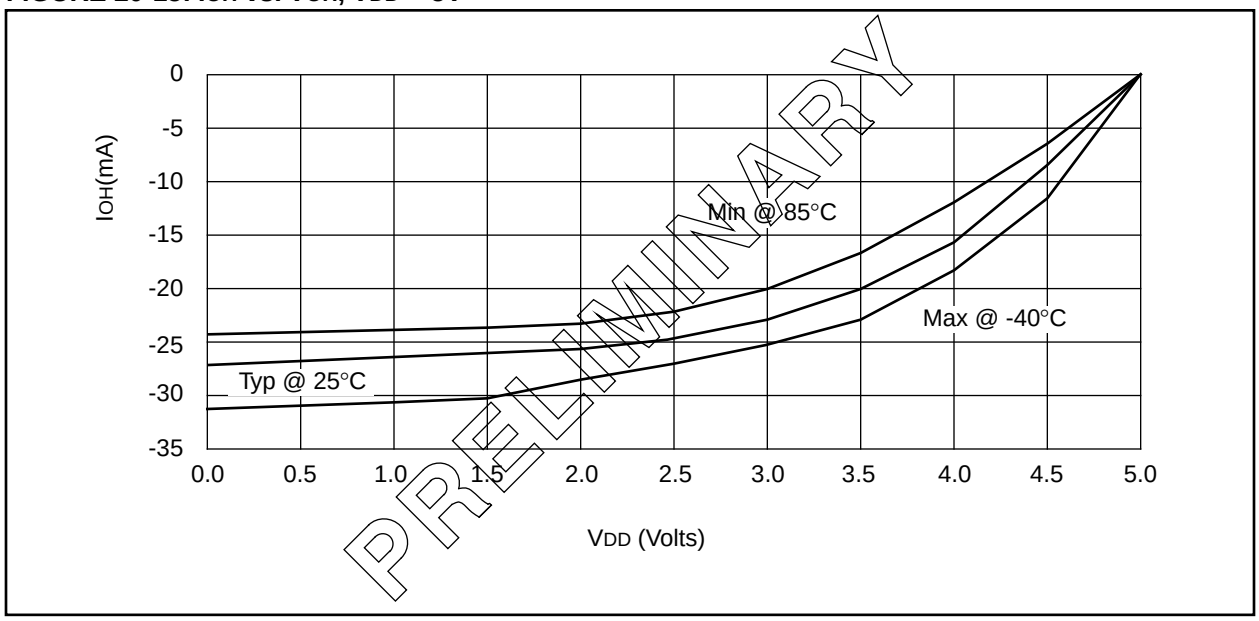
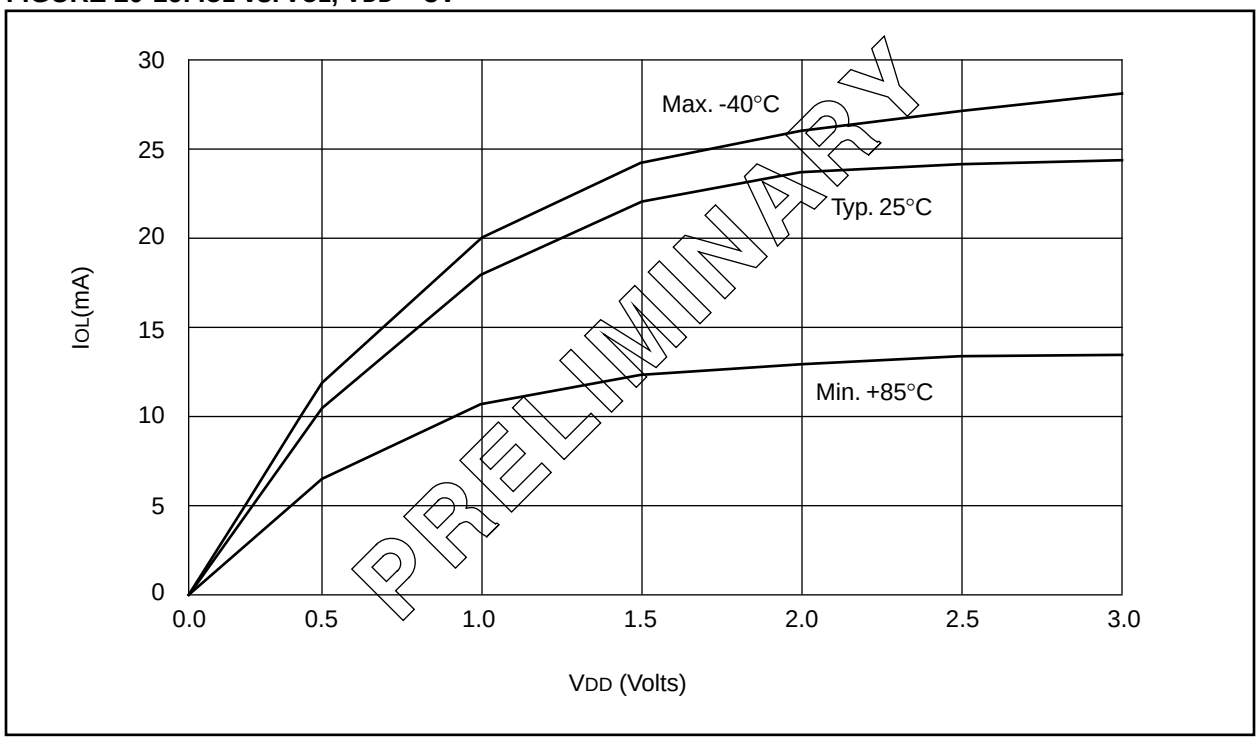
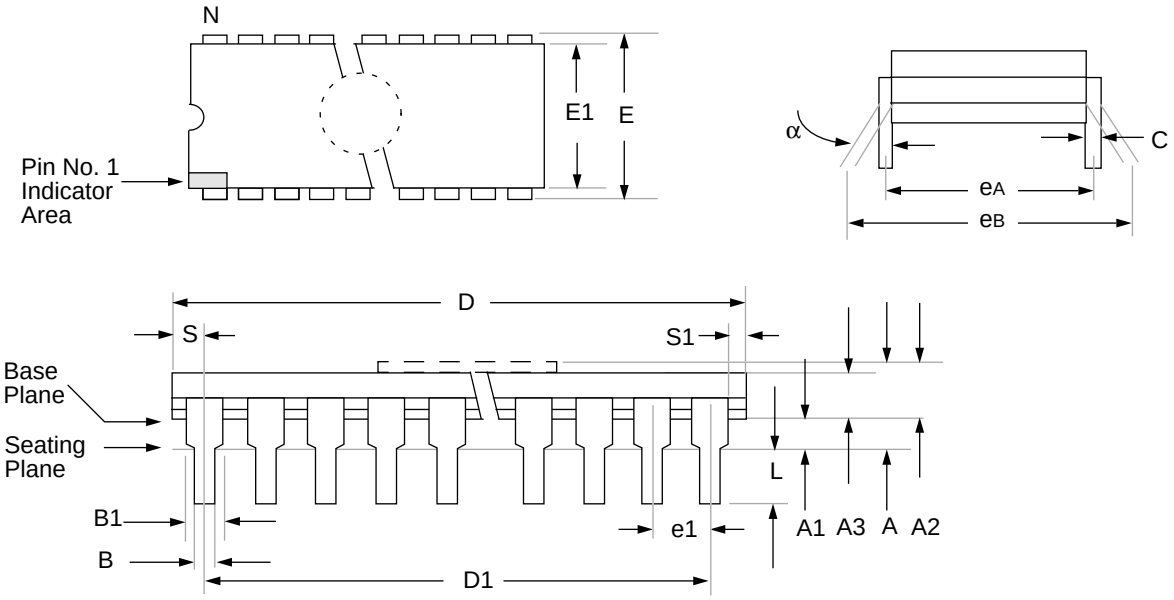


FIGURE 20-16: IOL vs. VOL, VDD = 3V



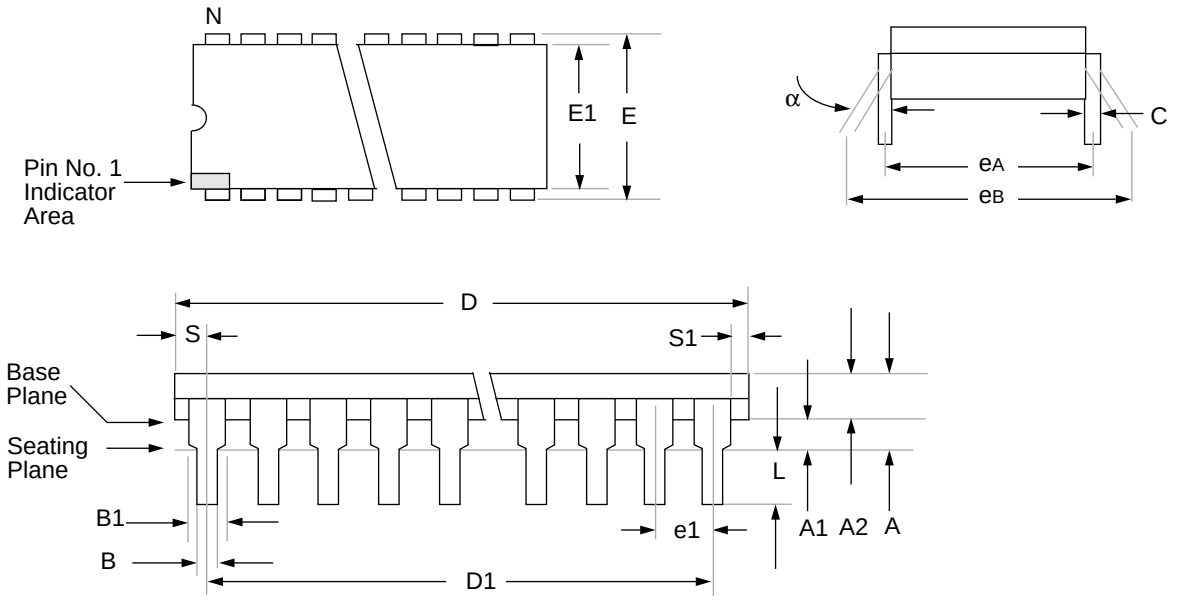
21.0 PACKAGING INFORMATION

21.1 40-Lead Ceramic CERDIP Dual In-line, and CERDIP Dual In-line with Window (600 mil)



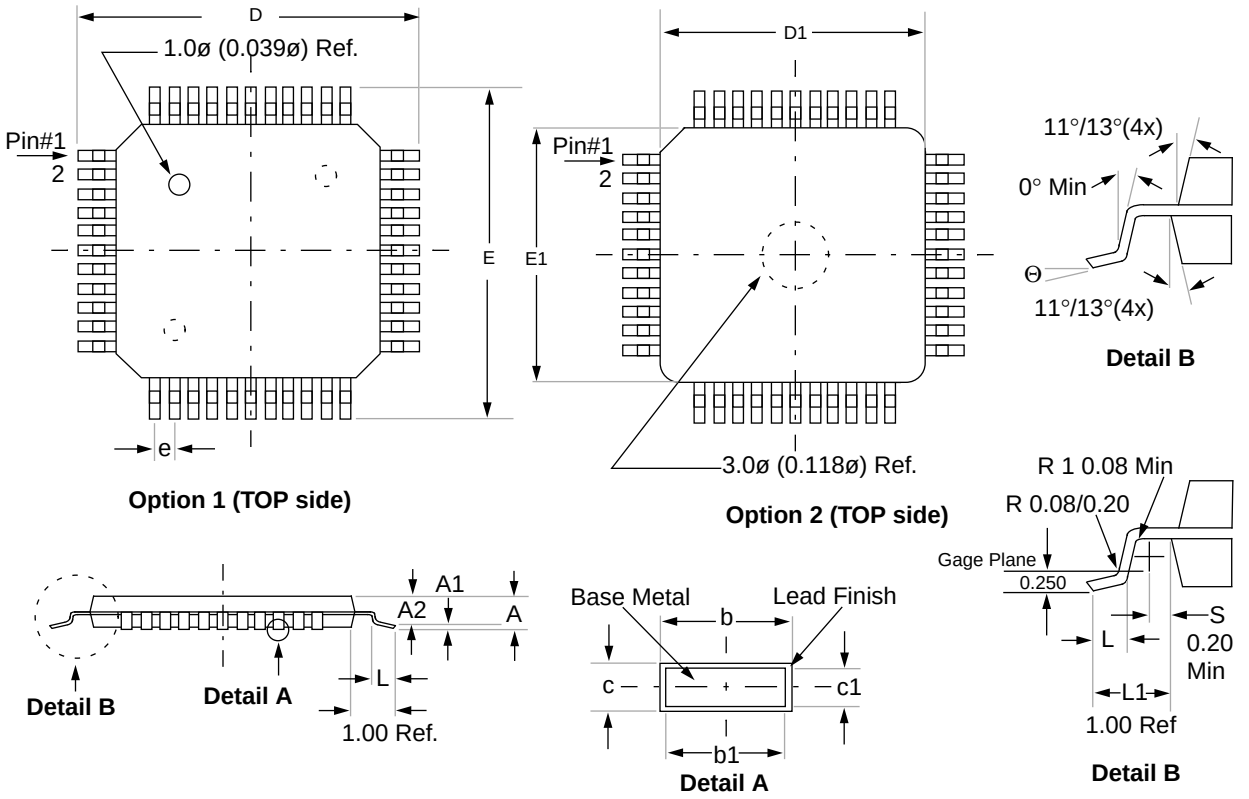
Package Group: Ceramic CERDIP Dual In-Line (CDP)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	4.318	5.715		0.170	0.225	
A1	0.381	1.778		0.015	0.070	
A2	3.810	4.699		0.150	0.185	
A3	3.810	4.445		0.150	0.175	
B	0.355	0.585		0.014	0.023	
B1	1.270	1.651	**Typical**	0.050	0.065	**Typical**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	51.435	52.705		2.025	2.075	
D1	48.260	48.260	**Reference**	1.900	1.900	**Reference**
E	15.240	15.875		0.600	0.625	
E1	12.954	15.240		0.510	0.600	
e1	2.540	2.540	**Reference**	0.100	0.100	**Reference**
eA	14.986	16.002	**Typical**	0.590	0.630	**Typical**
eB	15.240	18.034		0.600	0.710	
L	3.175	3.810		0.125	0.150	
N	40	40		40	40	
S	1.016	2.286		0.040	0.090	
S1	0.381	1.778		0.015	0.070	

21.2 40-Lead Plastic Dual In-line (600 mil)



Package Group: Plastic Dual In-Line (PLA)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	5.080		–	0.200	
A1	0.381	–		0.015	–	
A2	3.175	4.064		0.125	0.160	
B	0.355	0.559		0.014	0.022	
B1	1.270	1.778	**Typical**	0.050	0.070	**Typical**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	51.181	52.197		2.015	2.055	
D1	48.260	48.260	**Reference**	1.900	1.900	**Reference**
E	15.240	15.875		0.600	0.625	
E1	13.462	13.970		0.530	0.550	
e1	2.489	2.591	**Typical**	0.098	0.102	**Typical**
eA	15.240	15.240	**Reference**	0.600	0.600	**Reference**
eB	15.240	17.272		0.600	0.680	
L	2.921	3.683		0.115	0.145	
N	40	40		40	40	
S	1.270	–		0.050	–	
S1	0.508	–		0.020	–	

21.5 44-Lead Plastic Surface Mount (TQFP 10x10 mm Body 1.0/0.10 mm Lead Form)



Package Group: Plastic TQFP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
A	1.00	1.20		0.039	0.047	
A1	0.05	0.15		0.002	0.006	
A2	0.95	1.05		0.037	0.041	
D	11.75	12.25		0.463	0.482	
D1	9.90	10.10		0.390	0.398	
E	11.75	12.25		0.463	0.482	
E1	9.90	10.10		0.390	0.398	
L	0.45	0.75		0.018	0.030	
e	0.80 BSC			0.031 BSC		
b	0.30	0.45		0.012	0.018	
b1	0.30	0.40		0.012	0.016	
c	0.09	0.20		0.004	0.008	
c1	0.09	0.16		0.004	0.006	
N	44	44		44	44	
Θ	0°	7°		0°	7°	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25m/m (0.010”) per side. D1 and E1 dimensions including mold mismatch.

2: Dimension “b” does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08m/m (0.003”)max.

3: This outline conforms to JEDEC MS-026.

INDEX

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LIST OF EQUATIONS